

N-Channel Power MOSFET

600V, 0.5A, 10Ω

FEATURES

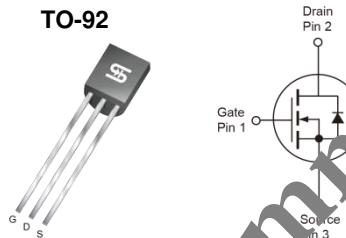
- 100% Avalanche Tested
- Pb-free plating
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

KEY PERFORMANCE PARAMETERS

PARAMETER	VALUE	UNIT
V _{DS}	600	V
R _{DS(on)} (max)	10	Ω
Q _g	6.1	nC

APPLICATIONS

- Power Supply
- AC/DC LED Lighting



ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V _{DS}	600	V
Gate-Source Voltage	V _{GS}	±30	V
Continuous Drain Current (Note 1)	I _D	0.5	A
T _C = 100°C		0.25	
Pulsed Drain Current (Note 2)	I _{DM}	2	A
Single Pulse Avalanche Energy (Note 3)	E _{AS}	5	mJ
Peak Diode Recovery dv/dt (Note 4)	dv/dt	4.5	V/ns
Total Power Dissipation @ T _C = 25°C	P _{DTOT}	2.5	W
Operating Junction Temperature	T _J	150	°C
Operating Junction and Storage Temperature Range	T _J , T _{STG}	- 55 to +150	°C

THERMAL PERFORMANCE

PARAMETER	SYMBOL	LIMIT	UNIT
Junction to Lead Thermal Resistance	R _{θJL}	50	°C/W
Junction to Ambient Thermal Resistance	R _{θJA}	110	°C/W

Thermal Performance Note: R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistances. The case-thermal reference is defined at the solder mounting surface of the drain pins. R_{θJA} is guaranteed by design while R_{θCA} is determined by the user's board design. R_{θJA} shown below for single device operation on FR-4 PCB with minimum recommended footprint in still air.

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ C$ unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static ^(Note 5)						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV_{DSS}	600	--	--	V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	$V_{GS(TH)}$	2.5	3.5	4.5	V
Gate Body Leakage	$V_{GS} = \pm 30V, V_{DS} = 0V$	I_{GSS}	--	--	± 100	nA
Zero Gate Voltage Drain Current	$V_{DS} = 600V, V_{GS} = 0V$	I_{DSS}	--	--	10	μA
Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 0.25A$	$R_{DS(ON)}$	--	8	10	Ω
Forward Transfer Conductance	$V_{DS} = 10V, I_D = 0.5A$	g_{fs}	--	0.8	--	S
Dynamic ^(Note 6)						
Total Gate Charge	$V_{DS} = 480V, I_D = 0.5A, V_{GS} = 10V$	Q_g	--	6.1	--	nC
Gate-Source Charge		Q_{gs}	--	1.4	--	
Gate-Drain Charge		Q_{gd}	--	3.3	--	
Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V, F = 1.0MHz$	C_{iss}	--	138	--	pF
Output Capacitance		C_{oss}	--	17.1	--	
Reverse Transfer Capacitance		C_{rss}	--	4.2	--	
Switching ^(Note 7)						
Turn-On Delay Time	$V_{GS} = 10V, I_D = 0.5A, V_{DD} = 300V, R_s = 5\Omega$	$t_{d(on)}$	--	7.7	--	ns
Turn-On Rise Time		t_r	--	6.8	--	
Turn-Off Delay Time		$t_{d(off)}$	--	15.3	--	
Turn-Off Fall Time		t_f	--	14.9	--	
Source-Drain Diode ^(Note 5)						
Source Current	Integral reverse diode in the MOSFET	I_S	--	--	0.5	A
Source Current (Pulse)		I_{SM}	--	--	2	A
Diode Forward Voltage	$I_S = 0.5A, V_{GS} = 0V$	V_{SD}	--	0.9	1.4	V

Notes:

1. Current limited by package
2. Pulse width limited by the maximum junction temperature
3. $V_{DD} = 50V, I_{AS}=0.5A, L=10mH, R_G=25\Omega$, Starting $T_J=25^\circ C$
4. $I_{SD}\leq 0.5A, di/dt\leq 200A/\mu s, V_{DD}\leq BV_{DSS}$, Starting $T_J=25^\circ C$
5. Pulse test: PW $\leq 300\mu s$, duty cycle $\leq 2\%$
6. For DESIGN AID ONLY, not subject to production testing.
7. Essentially Independent of Operating Temperature.

ORDERING INFORMATION

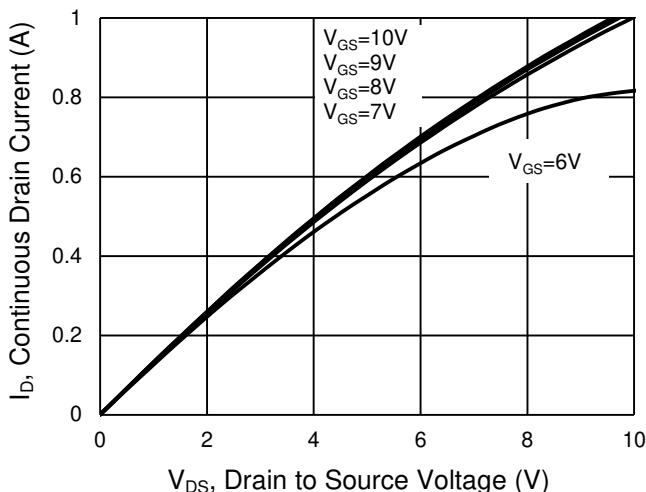
PART NO.	PACKAGE	PACKING
TSM1NB60SCT B0	TO-92	1,000pcs / Bulk
TSM1NB60SCT A3	TO-92	2,000pcs / Ammo
TSM1NB60SCT B0G	TO-92	1,000pcs / Bulk
TSM1NB60SCT A3G	TO-92	2,000pcs / Ammo

Not Recommended

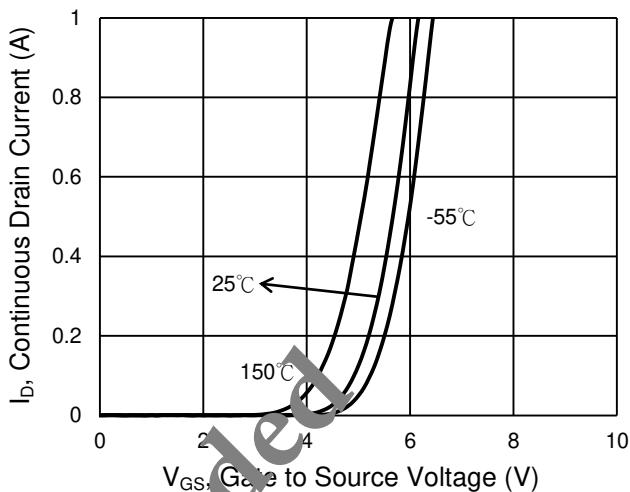
CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

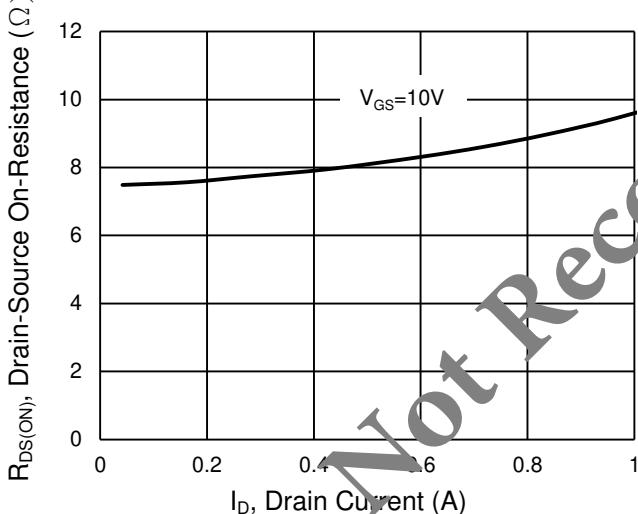
Output Characteristics



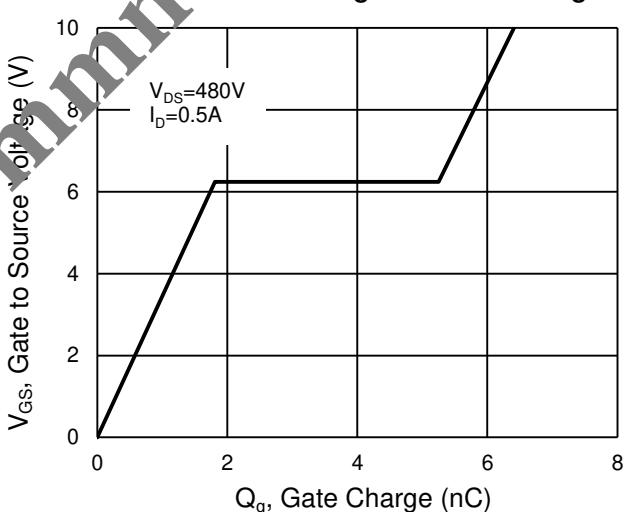
Transfer Characteristics



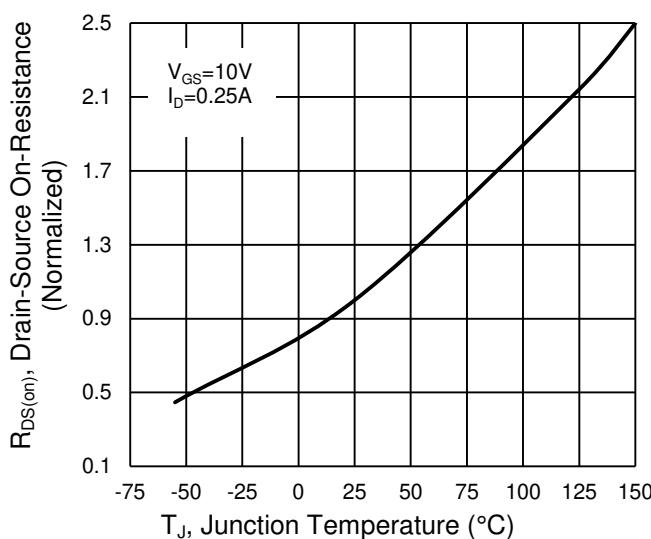
On-Resistance vs. Drain Current



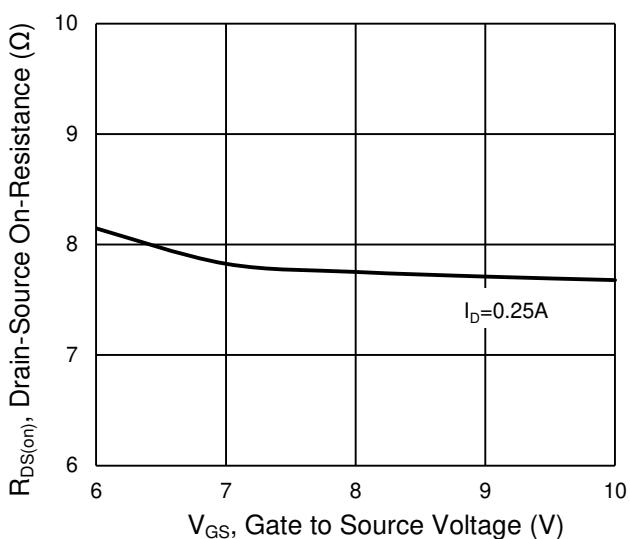
Gate-Source Voltage vs. Gate Charge



On-Resistance vs. Junction Temperature

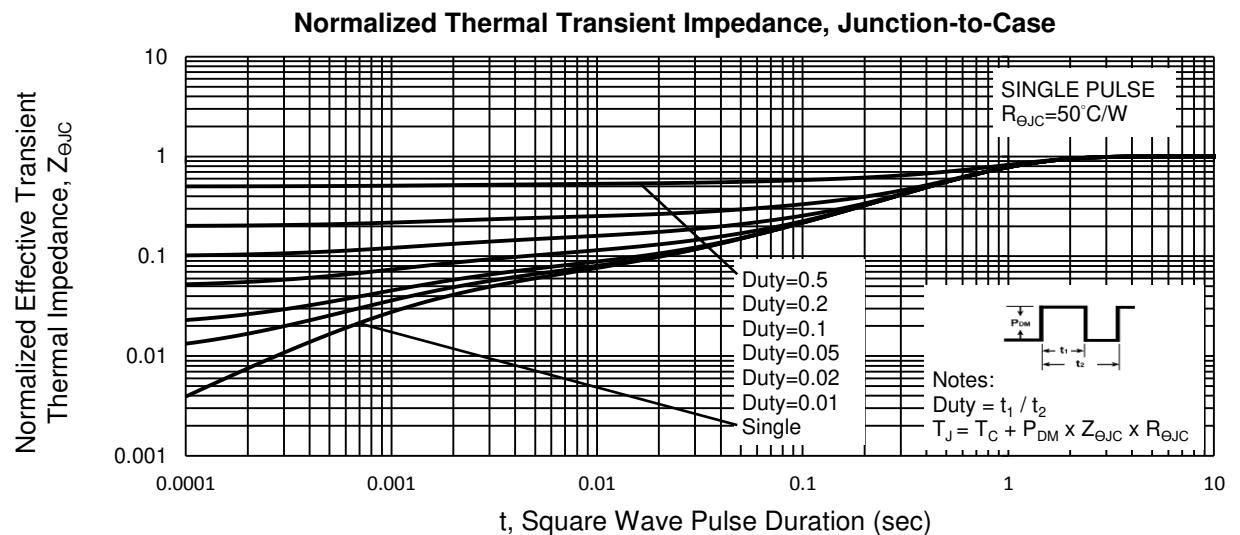
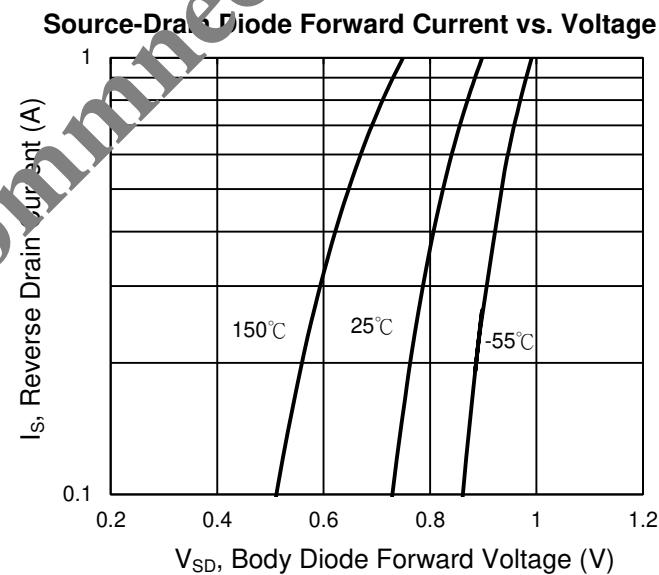
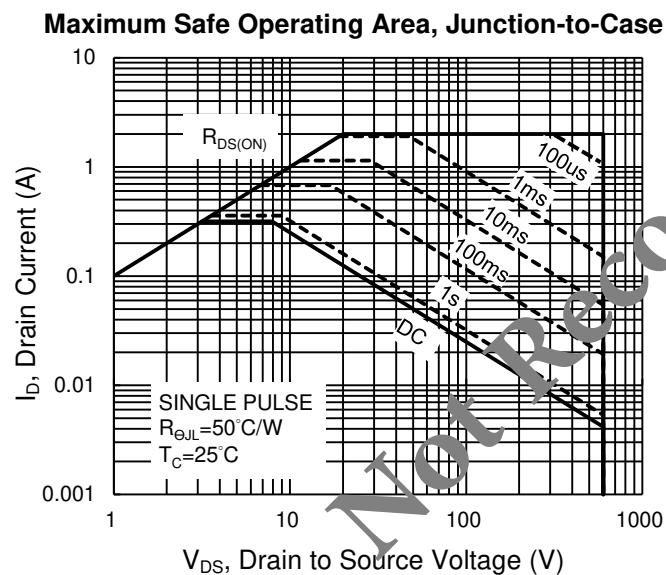
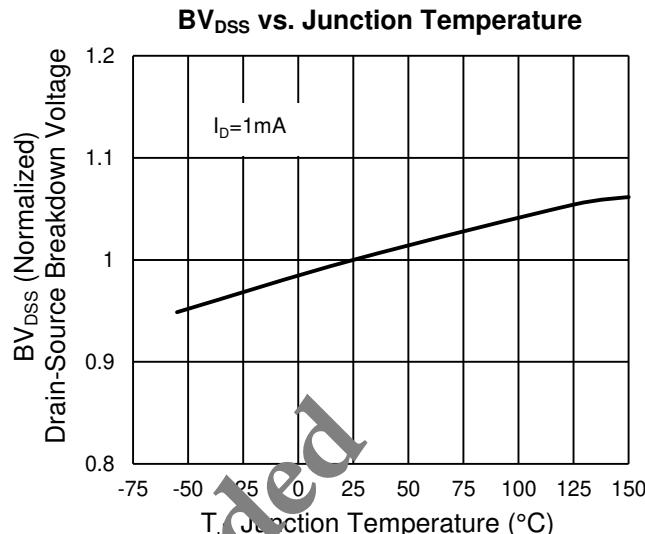
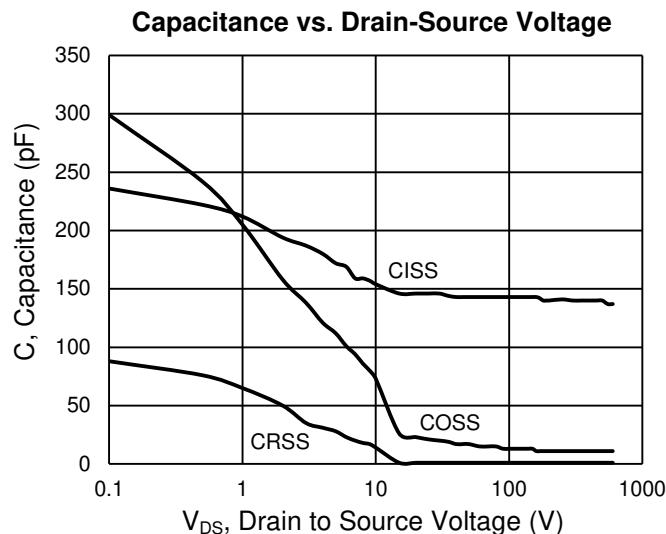


On-Resistance vs. Gate-Source Voltage

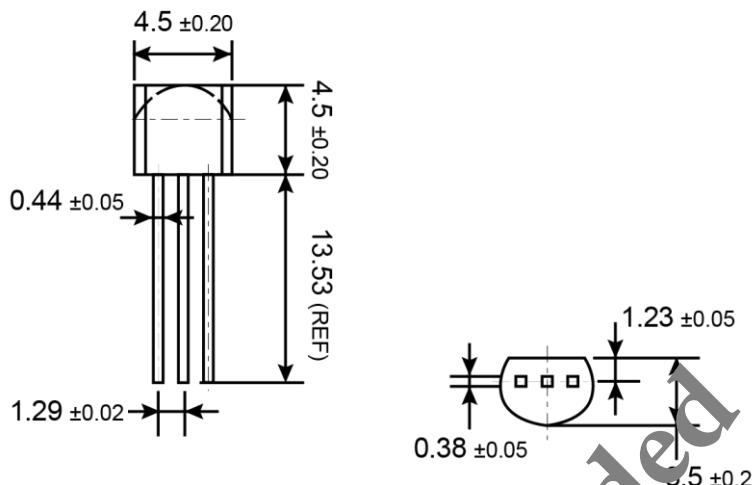


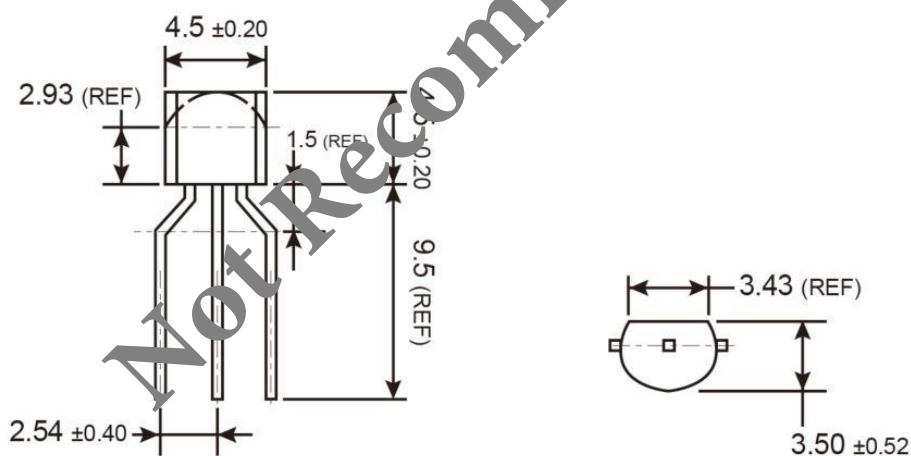
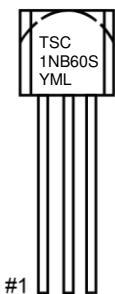
CHARACTERISTICS CURVES

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PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

TO-92

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TO-92 AMMO PACK

MARKING DIAGRAM

Y = Year Code

M = Month Code

(A=Jan, B=Feb, C=Mar, D=Apl, E=May, F=Jun, G=Jul, H=Aug,
I=Sep, J=Oct, K=Nov, L=Dec)
= Month Code for Halogen Free Product
(O=Jan, P=Feb, Q=Mar, R=Apl, S=May, T=Jun, U=Jul, V=Aug,
W=Sep, X=Oct, Y=Nov, Z=Dec)
L = Lot Code

Not Recommended

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